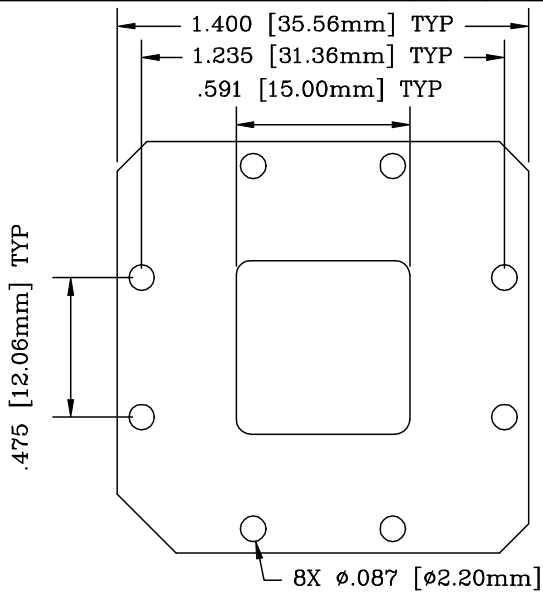
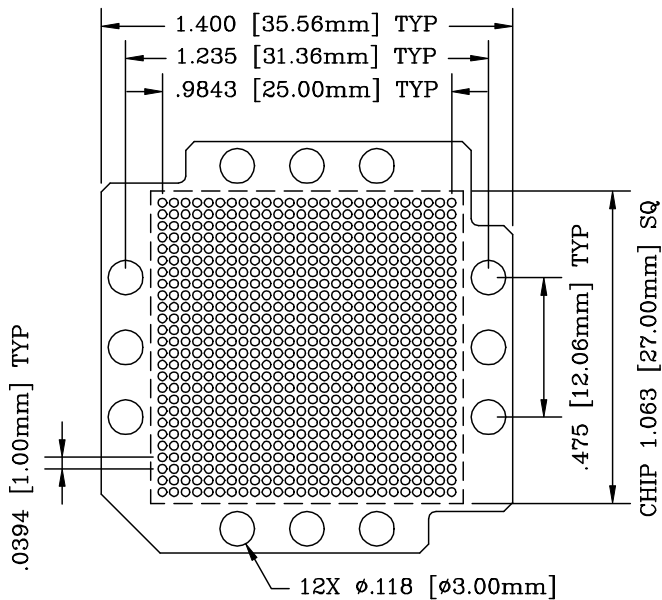


REV	DESCRIPTION	DATE	BY
A	NEW DRAWING	11/13/00	A.F.
B	UPDATED PADLAYOUT	03/16/01	H.N.
C	UPDATED DRAWING & DIMS	10/10/01	H.N.
D	UPDATED REC. PAD LAYOUT	10/14/02	H.N.

SKT1201
DOD 41201



RETENTION FRAME

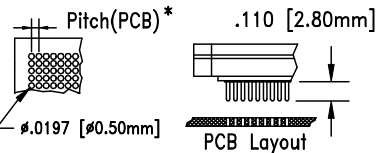


SOCKET

RECOMMENDED PAD LAYOUT

SOLDERTAIL STYLE	
REGULAR SMT STYLE XX = (-SM) YY = (-30)	RAISED SMT STYLE XX = (-RC) YY = (-29)
-30= standard SMT ("A" = .0315 [0.80mm]) -29= raised SMT ("A" = .126 [3.20mm])	
BALL DIAMETER FOR: -30(SM) = .0197 [0.50mm] TO .0276 [0.70mm] -29(RC) = .0197 [0.50mm] TO .0276 [0.70mm]	
BALL HEIGHT FOR: -30(SM) = .0118 [0.30mm] TO .0197 [0.50mm] -29(RC) = .0118 [0.30mm] TO .0197 [0.50mm]	

SOLDERTAIL = THRU HOLE STYLE
XX = (-ET)
YY = (-70)

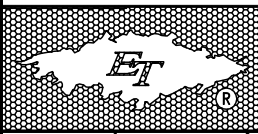


PIN DIAMETER FOR:
-70(ET) = .0114 [0.29mm]

PACKAGE SPECIFICATIONS

PIN COUNT	= 676
LEAD PITCH	= 1.00mm
GRID SIZE	= 26X26
PACKAGE SIZE	= 27.00mm SQUARE

ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE SPECIFIED



Emulation Technology, Inc.

VLSI and SMT ADAPTERS and ACCESSORIES

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SHEET: 1 OF 1	DATE: 10/14/02	REVISION: D	<b>ASSEMBLY DRAWING</b>
CHECKED: Perry Munroe	DRAWN: Hanh Nguyen	ITEM: S-MBG-26-676-XX	
Scale 1:2	DO NOT SCALE DRAWING	DESCRIPTION: BPW-676-3BG026-YY	

\* All Dimensions Are Nominal For A .0394 [1.00mm] Pitch BGA Package